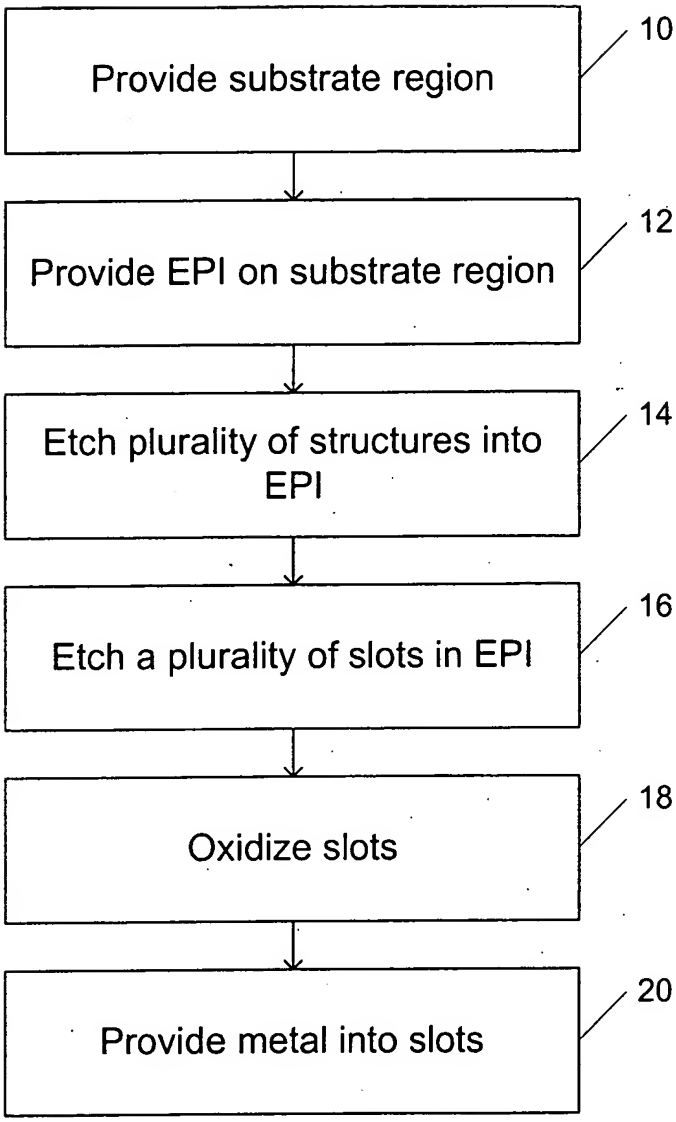

Provide substrate region
10
Provide EPI on substrate region
12
Etch plurality of structures into EPI
14
Etch a plurality of slots in EPI
16
Oxidize slots
18
Provide metal into slots
20

Fig. 1

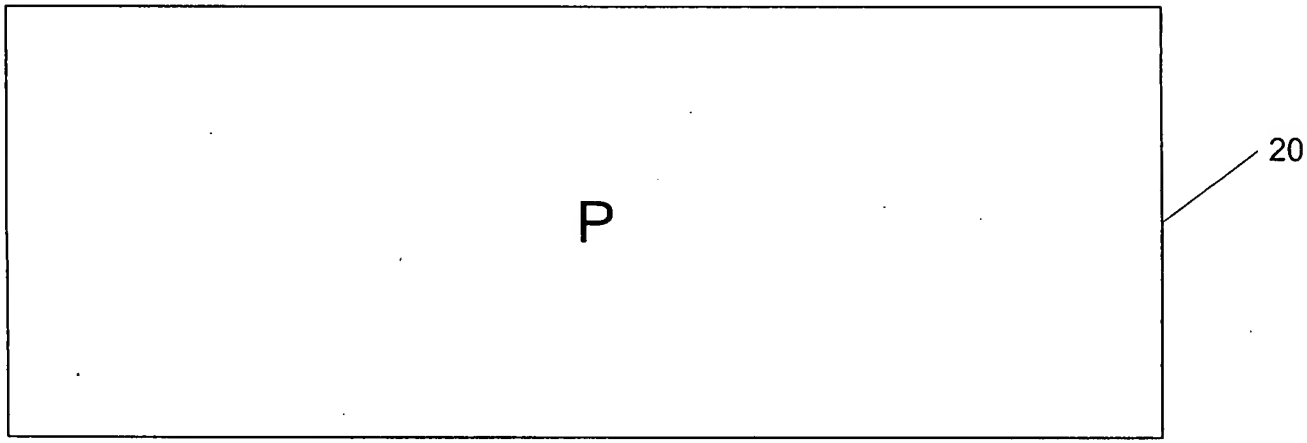


Fig. 2a

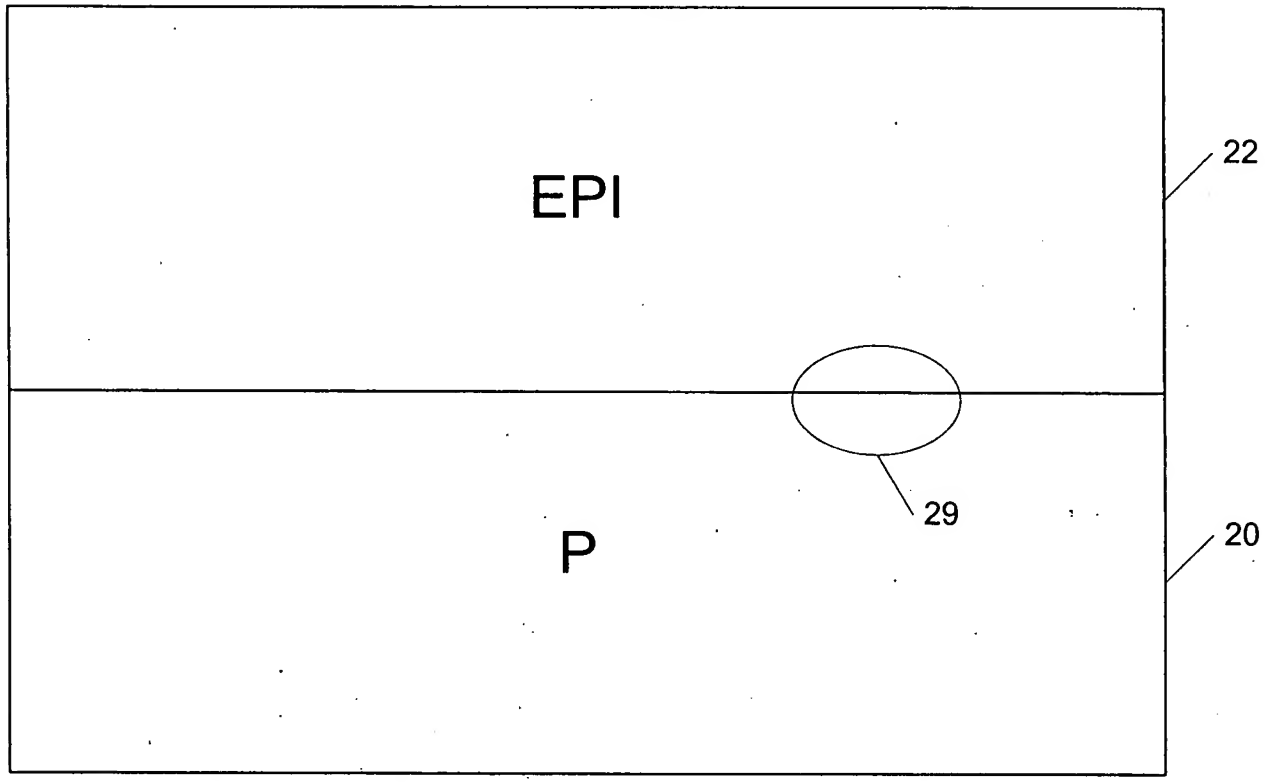


Fig. 2b

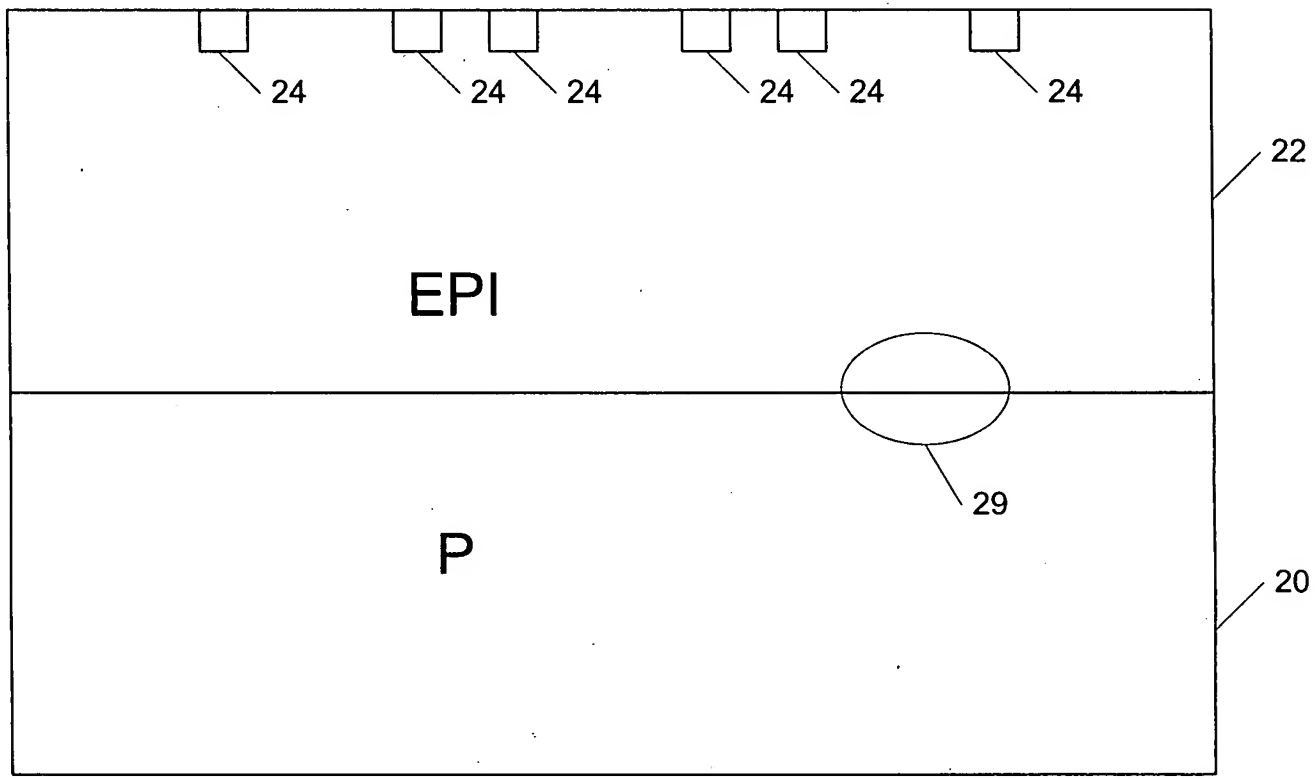


Fig. 2c

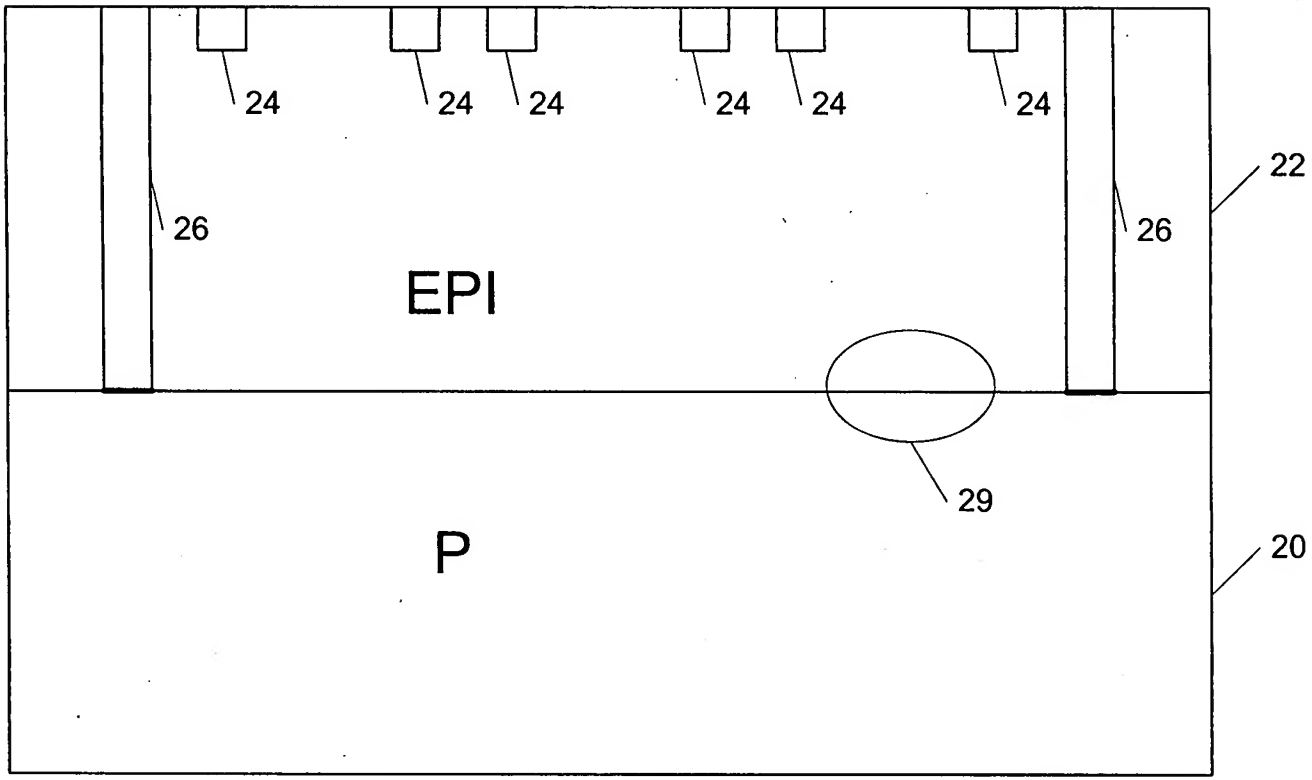


Fig. 2d

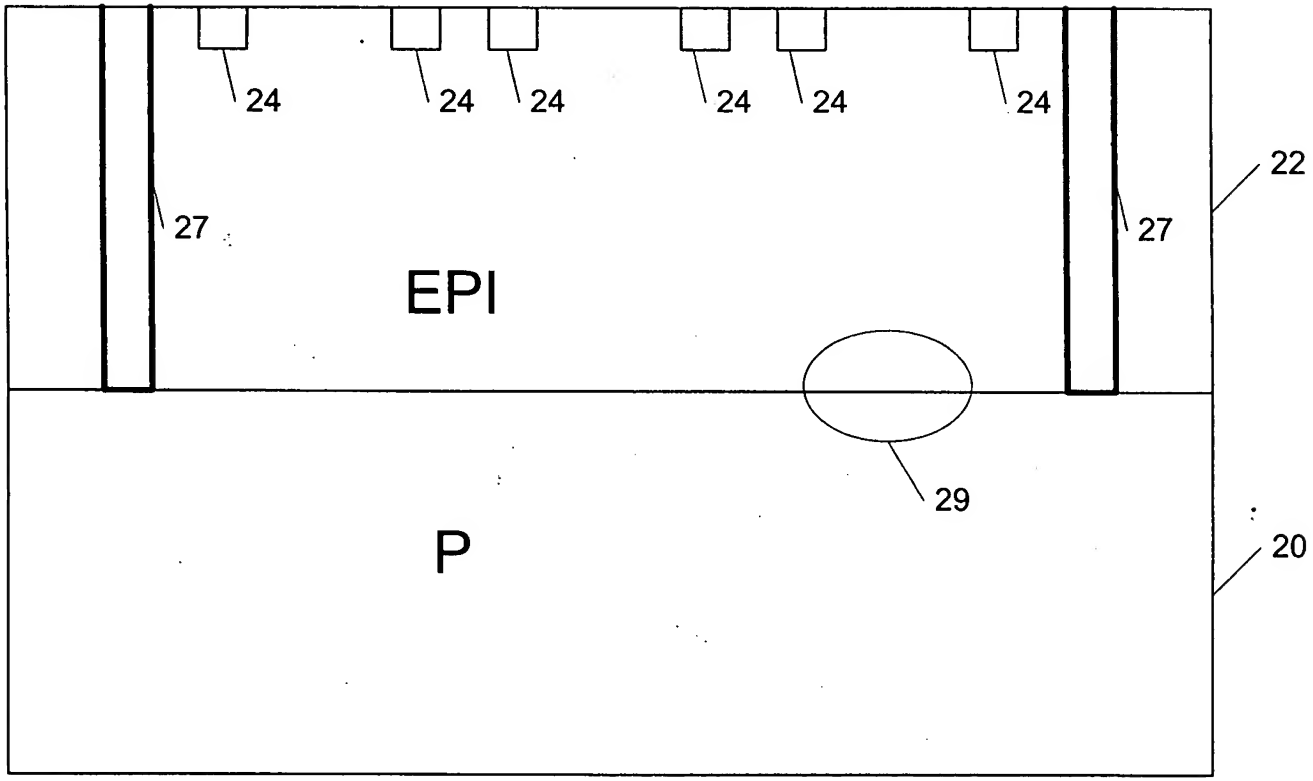


Fig. 2e

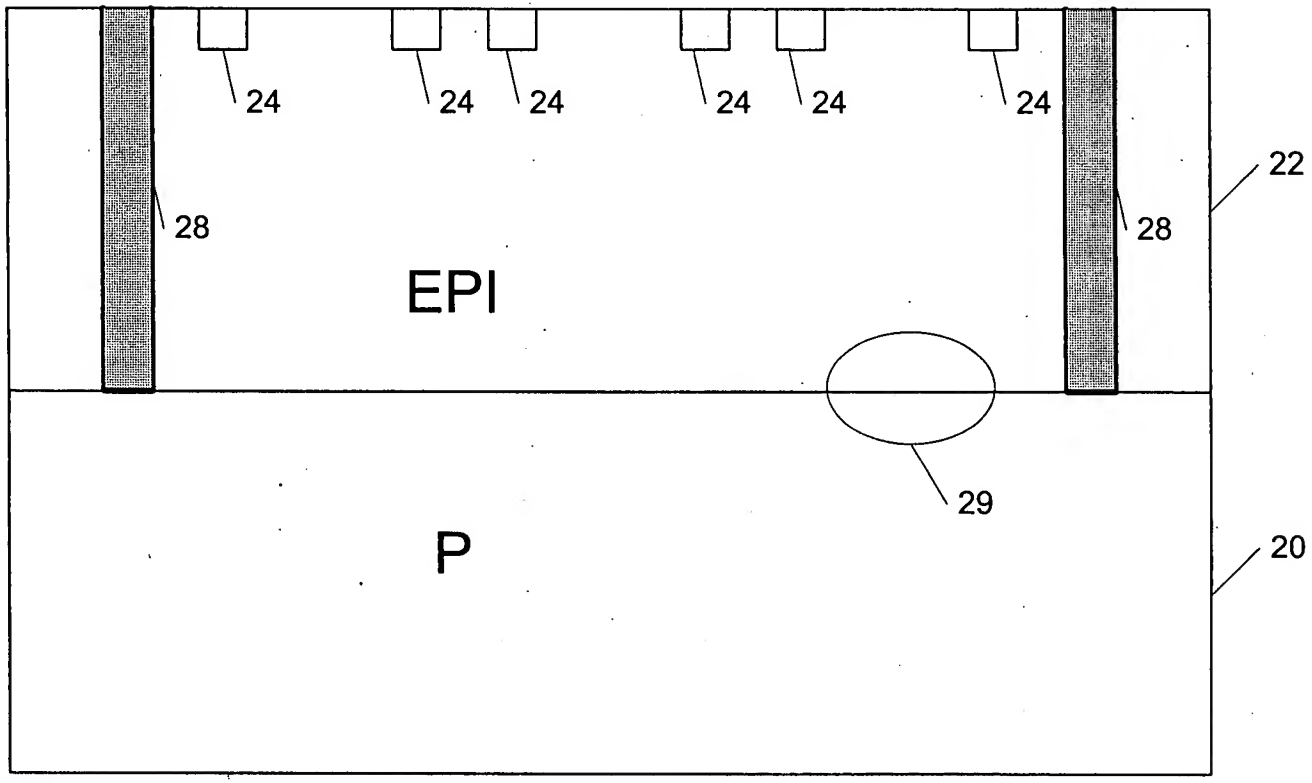


Fig. 2f

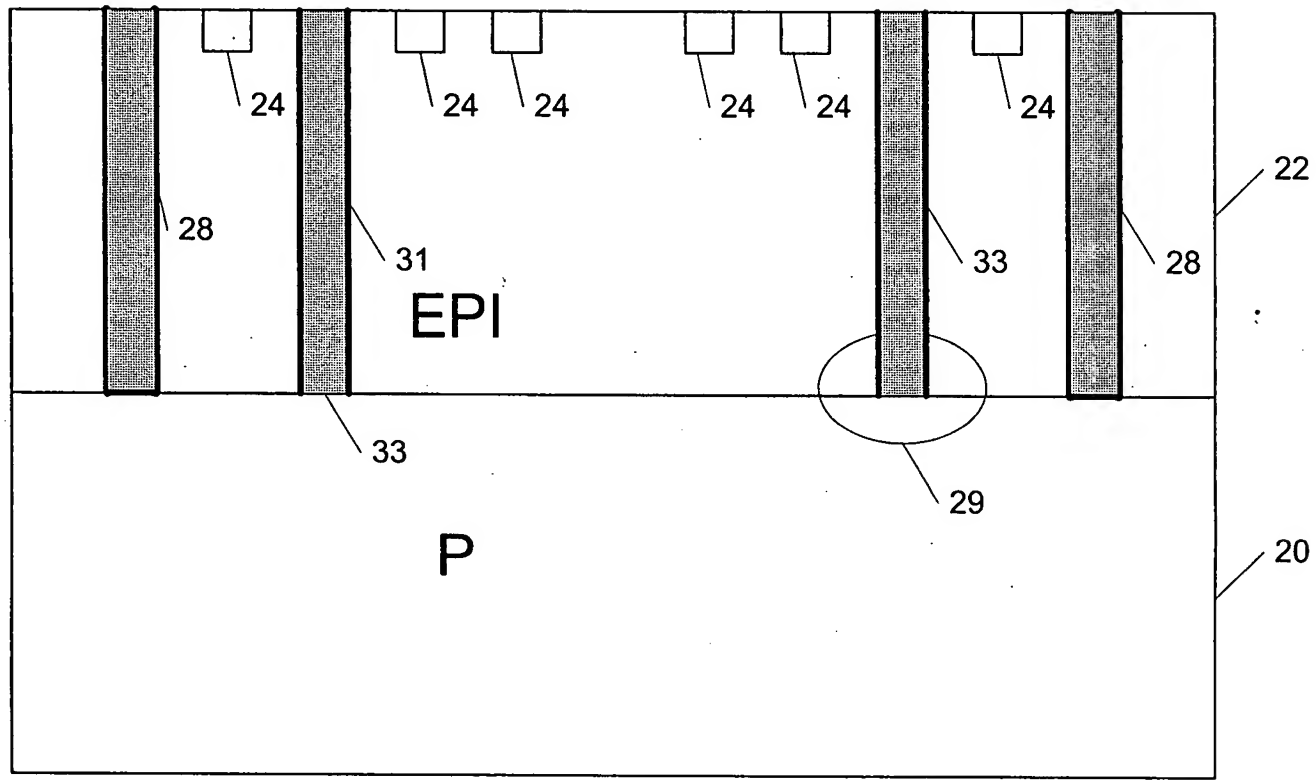


Fig. 2g

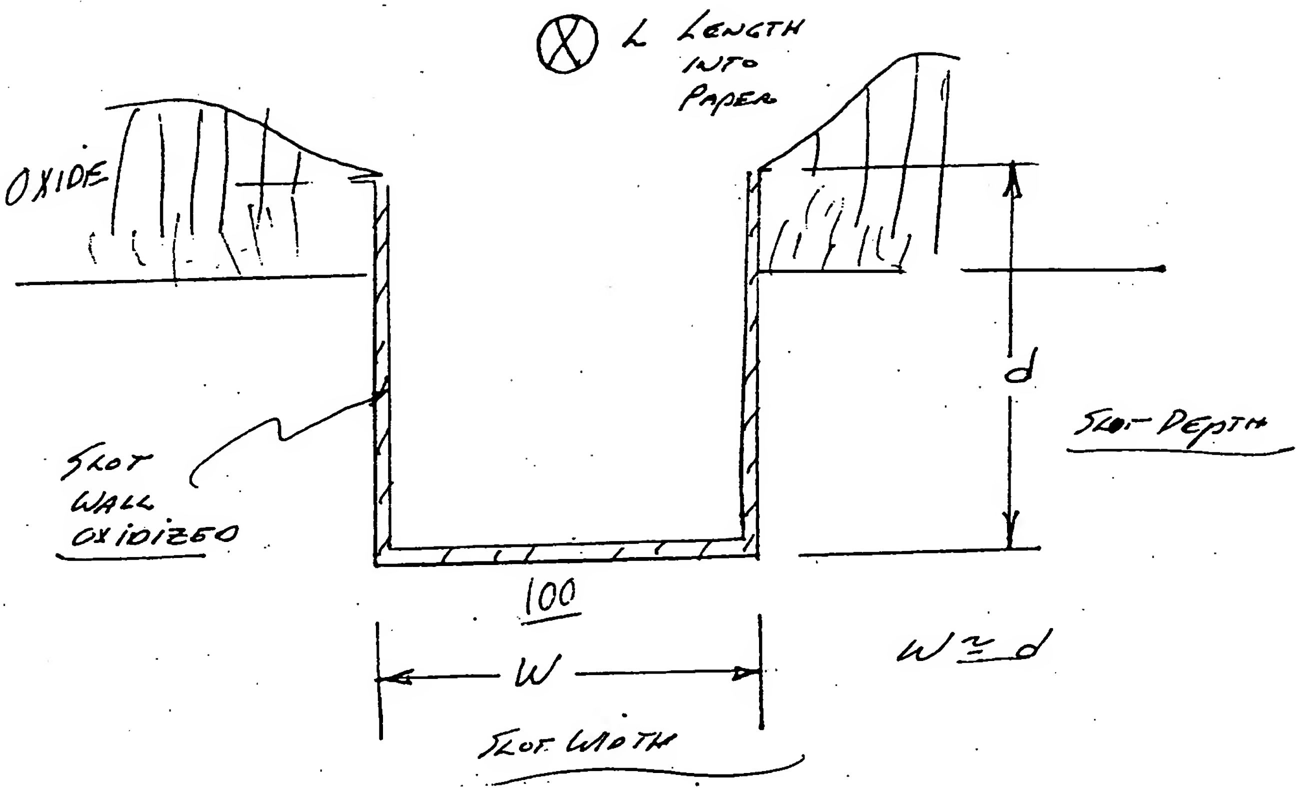


Fig. 3

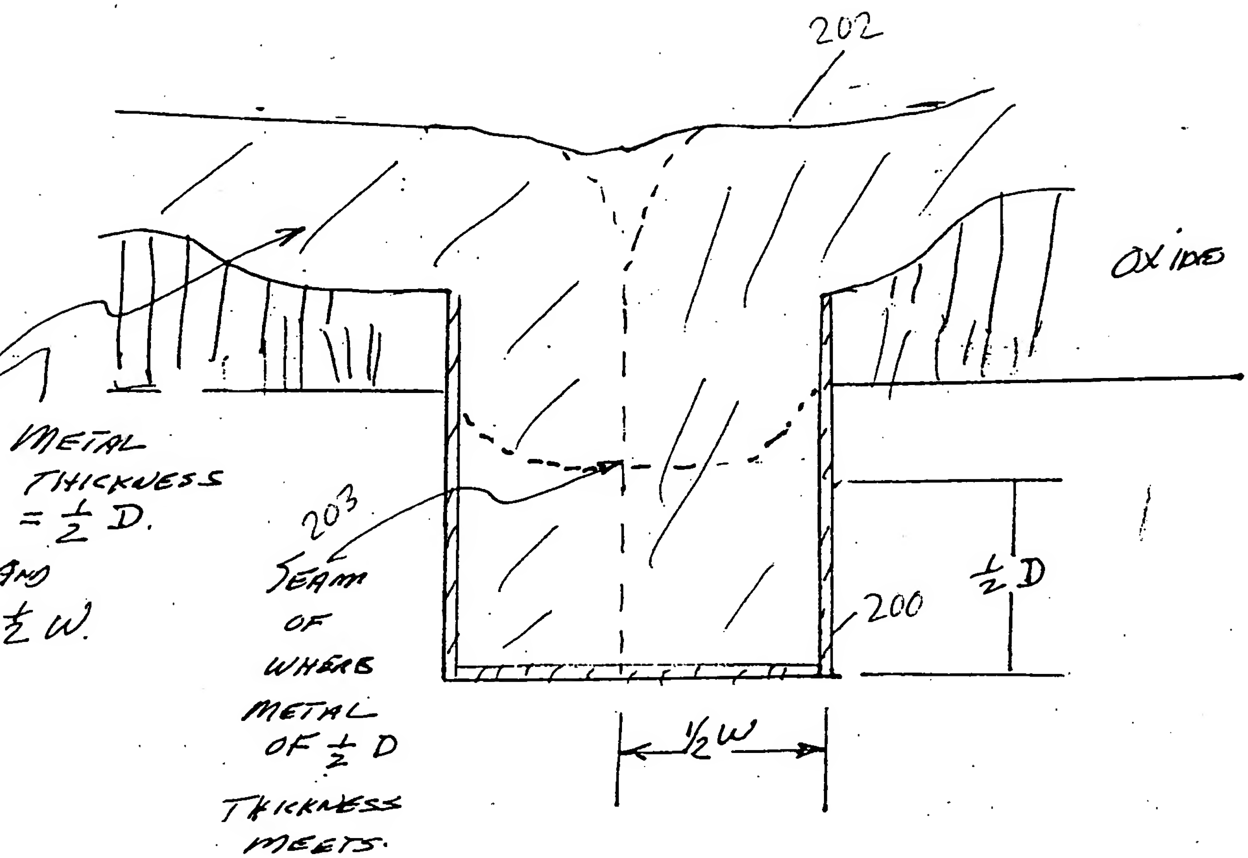
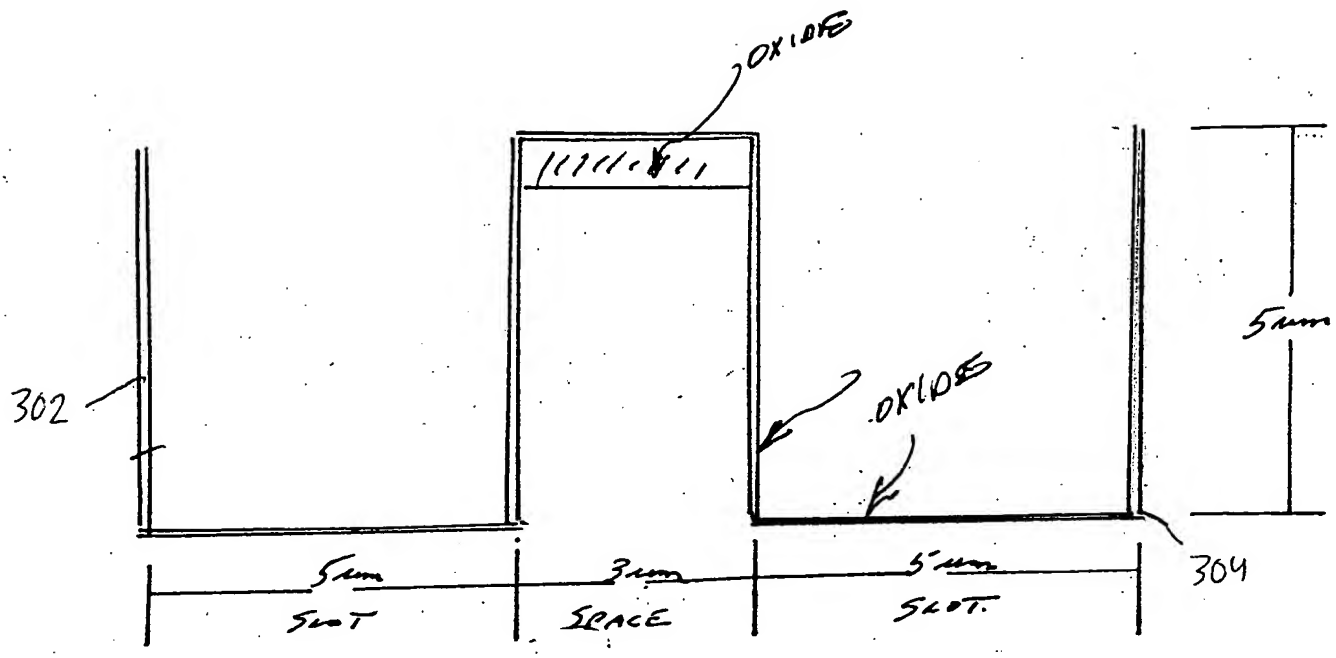
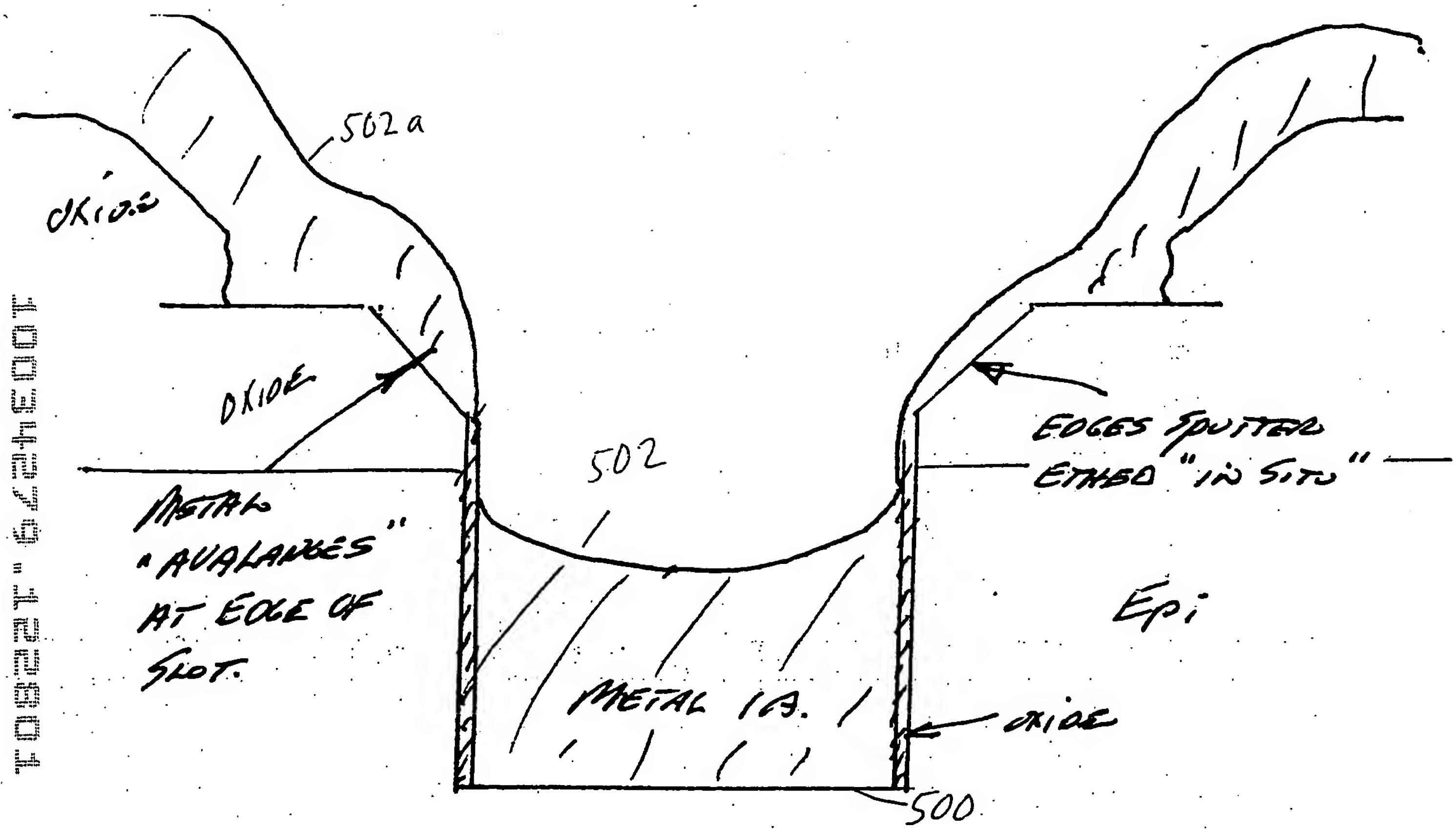


Fig. 4



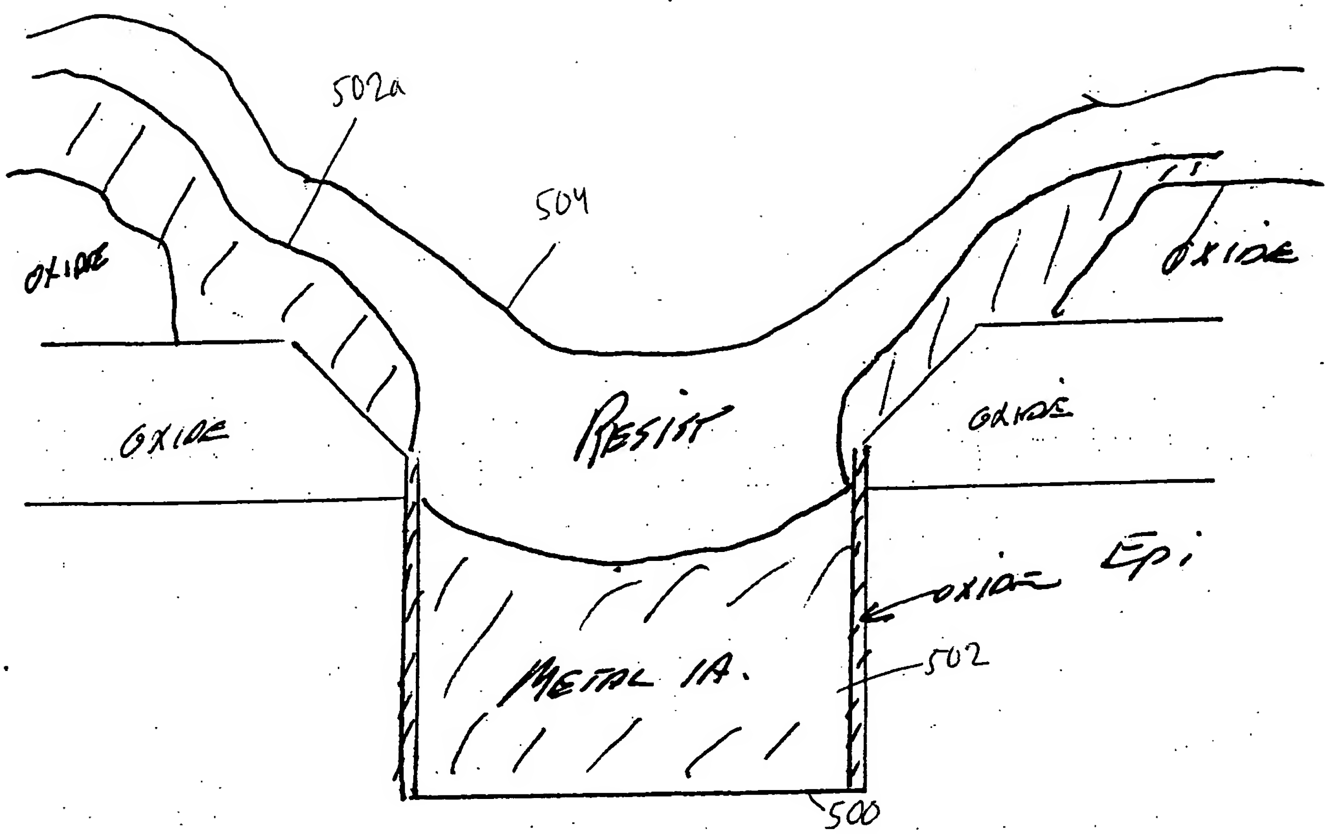
DOUBLE SLOT FOR
DOUBLE WIDTH OF METAL.
3um SPACE BETWEEN SLOTS

Fig. 4a



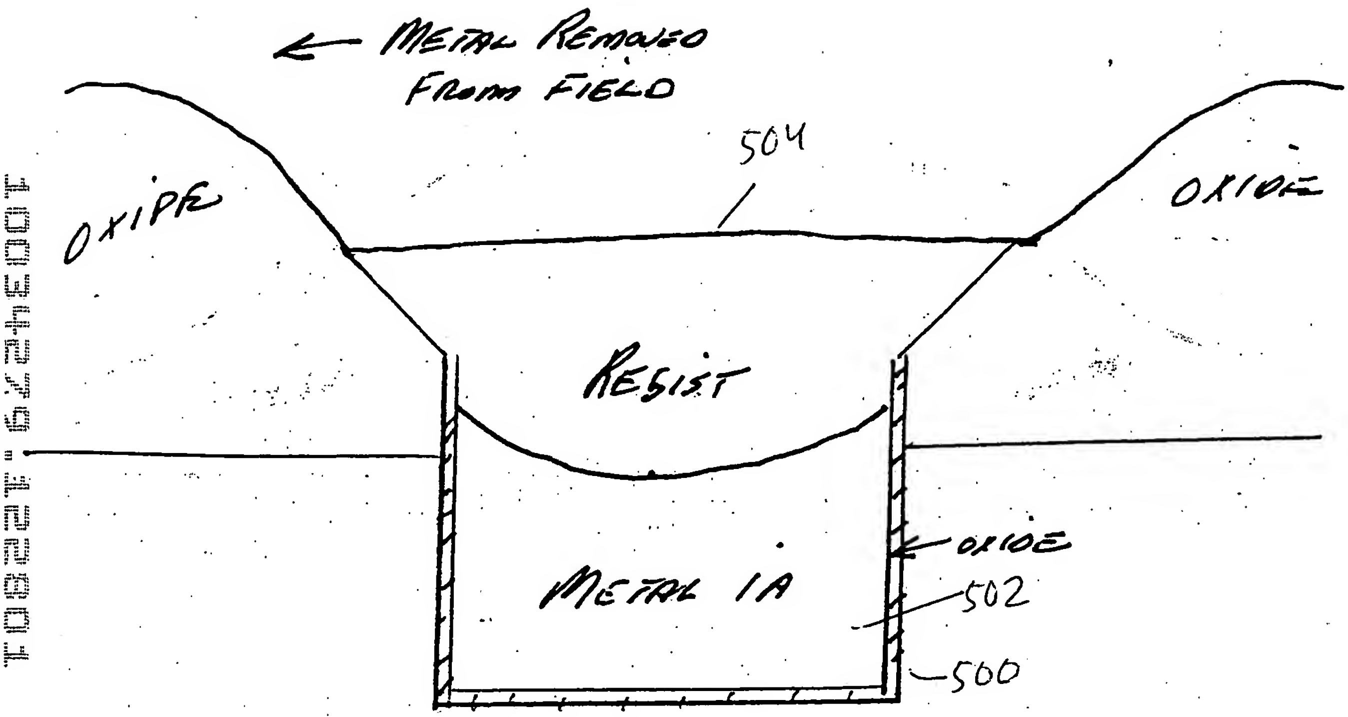
PRIOR TO METAL 1A BEING SPUTTERED, THE EDGES OF THE OXIDES ARE SPUTTERED ET..D "IN SITU" & 1A DEPOSITED

Fig. 5



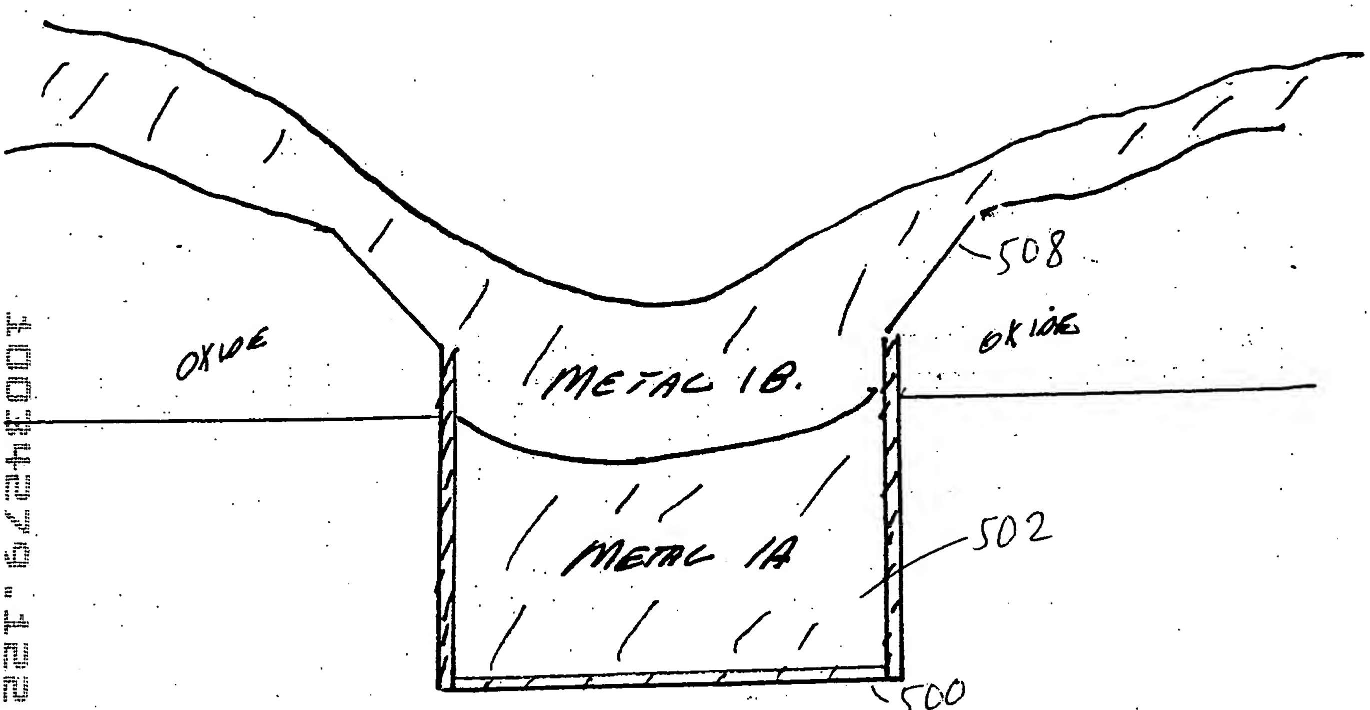
RESIST COATING - THICK IN THE SLOTS

Fig. 6



RESIST PLANAR ETCHED.
LEAVING RESIST IN SLOTS
FIELD METAL ETCHED OFF.

Fig. 7



RESIST STRIPPED & SECOND
METAL 1B SPUTTER DEPOSITED

Fig. 8

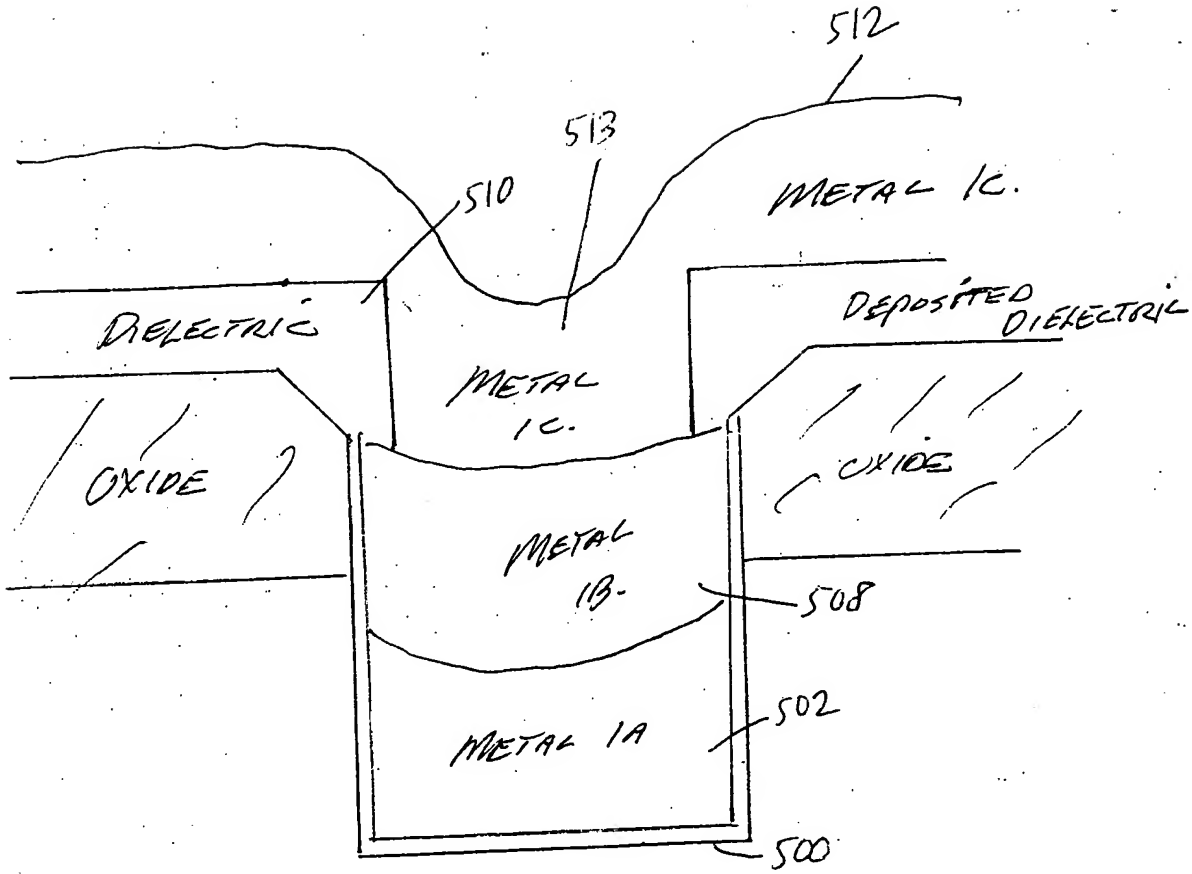


Fig. 9

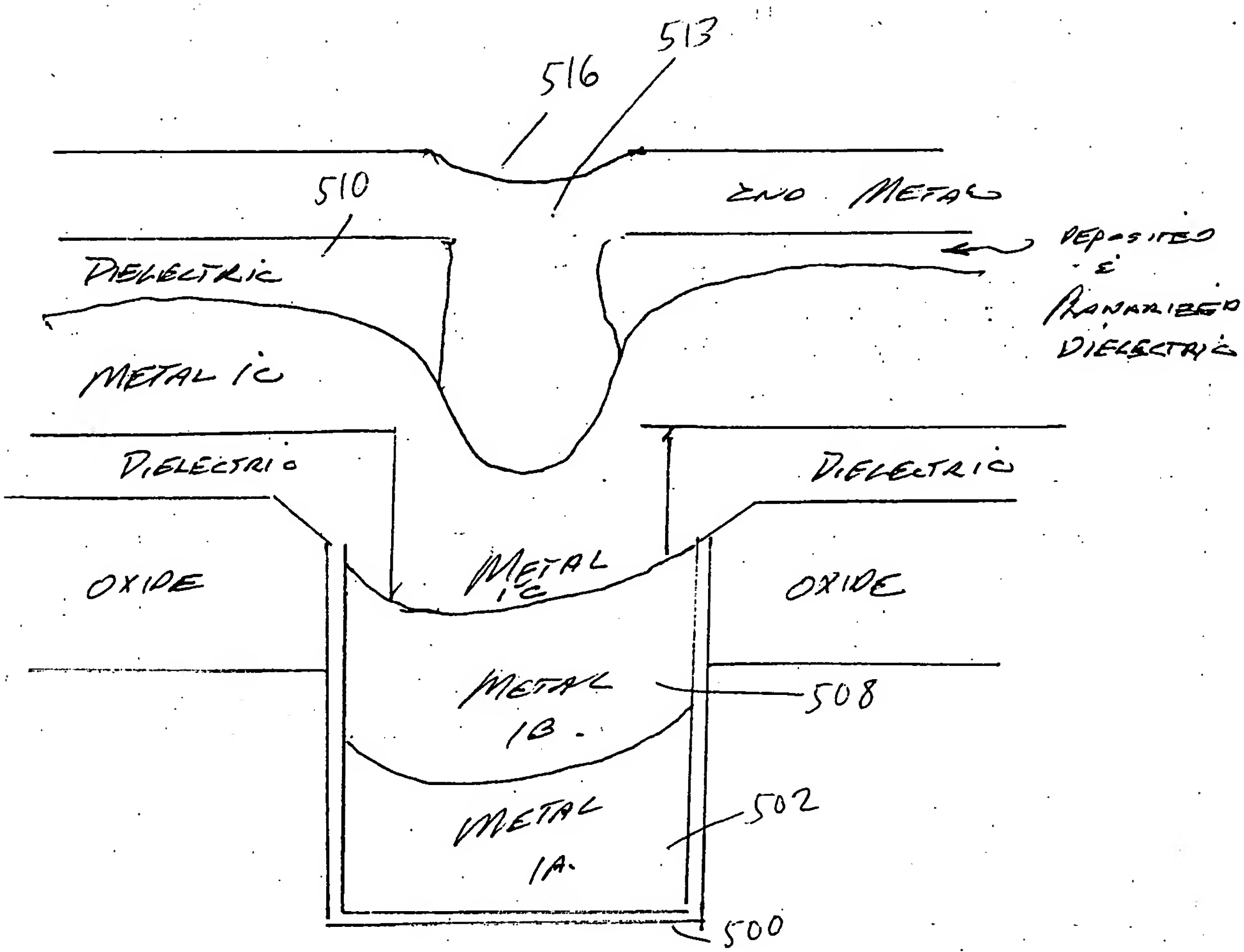
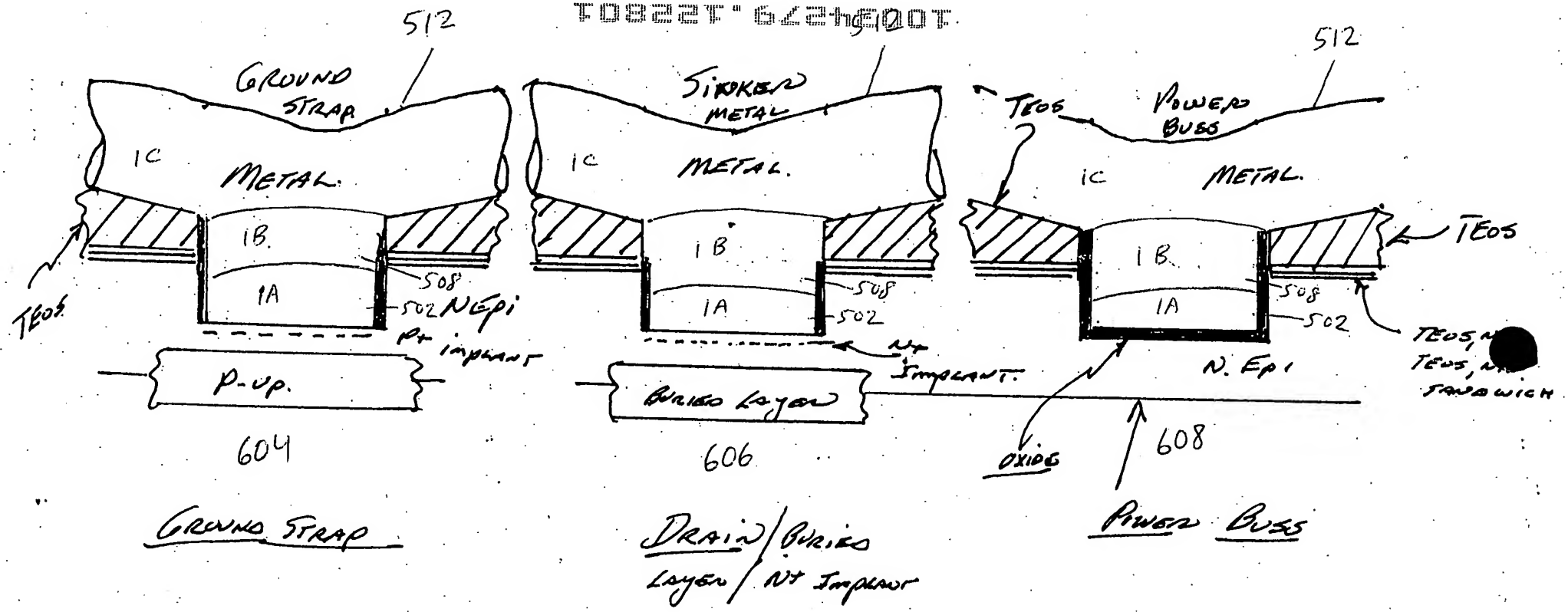

516
513
510
2ND METAL
DIELECTRIC
DEPOSITED & PLANARIZED DIELECTRIC
METAL 1C
DIELECTRIC
DIELECTRIC
OXIDE
METAL 1C
OXIDE
METAL 1B
508
METAL 1A
502
500

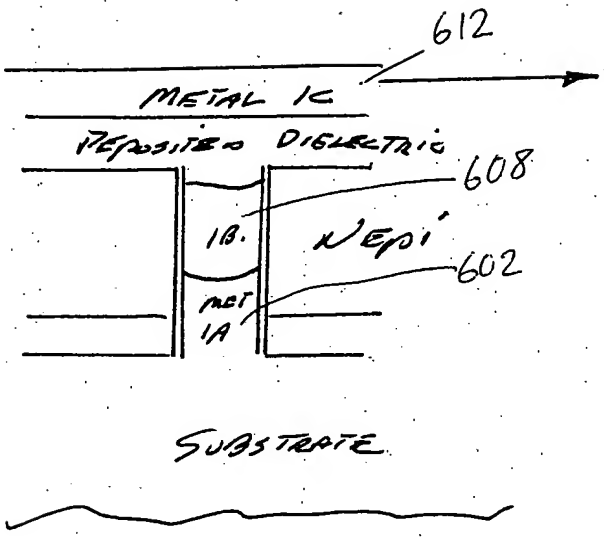
Fig. 10



GROUND STRAP / POWER BUSS / DRAIN METAL SINKER

SHOWN AFTER LAYERS OF DIELECTRIC FOLLOWED BY 9000 Å TEOS – POLISH.– SLOT MASK – METAL.
METAL 1.5 – 2.0 μm deposited

Fig. 11 POWER METAL.



METAL IC CONNECTS AN ISOLATED ISLAND TO ADJACENT ISOLATED EPI ISLANDS AND CROSSES OVER THE ISOLATION GROUND STRAP BY NOT OPENING A VIA IN THIS PORTION TO ALLOW IC TO BE ISOLATED FROM GROUND.

Fig. 12